Oerlikon Deep Si Etcher

Manager: Meredith Metzler
Backup: Vince Genova
Backup: Rob Ilic

Work Phone
254-4934
254-4907
254-4894

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

Safety
- No unusual hazards
- No buddy system restrictions

Process Restrictions

Material Restrictions
- 4" wafers only
- Thermal/GSI oxide, resist, Al2O3, Cr etch masks
- No other metals exposed

Parameter Restrictions
- Only modify iteration count in DSE III IAT process

Scheduling / Sign-up Restrictions
- Limit one 2 hour block between 8 AM and 6 PM
- Total reserved time limited to 6 hours

Requirements (Do Every Time)
- Remove 5 mm edge bead
- Run minimum 10 min Standard Clean on blank silicon prior to process
- Remain in lab when plasma is on

Prohibitions (Never Do)

Common Problems

Problem: Root Cause: Solution:

Other Comments or Cautions

Printed: 5/12/2010